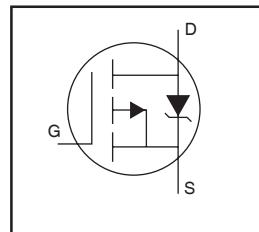
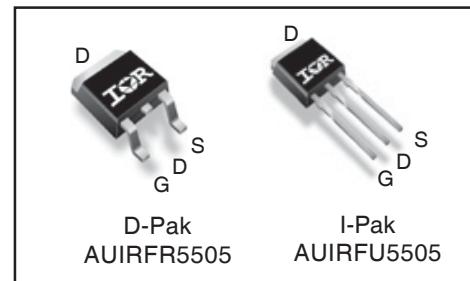


Features

- Advanced Planar Technology
- Low On-Resistance
- P-Channel
- Dynamic dV/dT Rating
- 150°C Operating Temperature
- Fast Switching
- Fully Avalanche Rated
- Repetitive Avalanche Allowed up to T_{jmax}
- Lead-Free, RoHS Compliant
- Automotive Qualified *



HEXFET® Power MOSFET		
$V_{(BR)DSS}$	-55V	
$R_{DS(on)}$ max.	0.11Ω	
I_D	-18A	



G	D	S
Gate	Drain	Source

Description

Specifically designed for Automotive applications, this Cellular design of HEXFET® Power MOSFETs utilizes the latest processing techniques to achieve low on-resistance per silicon area. This benefit combined with the fast switching speed and ruggedized device design that HEXFET power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in Automotive and a wide variety of other applications.

Absolute Maximum Ratings

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature (T_A) is 25°C, unless otherwise specified.

	Parameter	Max.	Units
I_D @ $T_C = 25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ -10\text{V}$	-18	A
I_D @ $T_C = 100^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ -10\text{V}$	-11	
I_{DM}	Pulsed Drain Current ①	-64	
$P_D @ T_C = 25^\circ\text{C}$	Power Dissipation	57	W
	Linear Derating Factor	0.45	W/°C
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{AS}	Single Pulse Avalanche Energy(Thermally limited) ②	150	mJ
I_{AR}	Avalanche Current ①	-9.6	A
E_{AR}	Repetitive Avalanche Energy ①	5.7	mJ
dv/dt	Peak Diode Recovery dv/dt ③	-5.0	V/ns
T_J	Operating Junction and	-55 to + 150	°C
T_{STG}	Storage Temperature Range		
	Soldering Temperature, for 10 seconds	300 (1.6mm from case)	

Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	—	2.2	°C/W
$R_{\theta JA}$	Junction-to-Ambient (PCB mount) **	—	50	
$R_{\theta JA}$	Junction-to-Ambient	—	110	

HEXFET® is a registered trademark of International Rectifier.

*Qualification standards can be found at <http://www.irf.com/>

Static Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(\text{BR})\text{DSS}}$	Drain-to-Source Breakdown Voltage	-55	—	—	V	$V_{GS} = 0V, I_D = -250\mu\text{A}$
$\Delta V_{(\text{BR})\text{DSS}}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	-0.049	—	V/ $^\circ\text{C}$	Reference to 25°C , $I_D = -1\text{mA}$
$R_{DS(\text{on})}$	Static Drain-to-Source On-Resistance	—	—	0.11	Ω	$V_{GS} = -10V, I_D = -9.6\text{A}$ ④
$V_{GS(\text{th})}$	Gate Threshold Voltage	-2.0	—	-4.0	V	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$
g_{fs}	Forward Transconductance	4.2	—	—	S	$V_{DS} = -25V, I_D = -9.6\text{A}$ ⑥
I_{DSS}	Drain-to-Source Leakage Current	—	—	-25	μA	$V_{DS} = -55V, V_{GS} = 0V$
		—	—	-250		$V_{DS} = -44V, V_{GS} = 0V, T_J = 150^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	100	nA	$V_{GS} = -20V$
	Gate-to-Source Reverse Leakage	—	—	-100		$V_{GS} = 20V$

Dynamic Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

Q_g	Total Gate Charge	—	—	32	nC	$I_D = -9.6\text{A}$ $V_{DS} = -44V$ $V_{GS} = -10V$, See Fig 6 and 13 ④
Q_{gs}	Gate-to-Source Charge	—	—	7.1		
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	—	15		
$t_{d(\text{on})}$	Turn-On Delay Time	—	12	—		$V_{DD} = -28V$ $I_D = -9.6\text{A}$
t_r	Rise Time	—	28	—	ns	$R_G = 2.6 \Omega$ $R_D = 2.8\Omega$, See Fig.10 ④
$t_{d(\text{off})}$	Turn-Off Delay Time	—	20	—		
t_f	Fall Time	—	16	—		
L_D	Internal Drain Inductance	—	4.5	—		Between lead, 6mm (0.25in.) from package and center of die contact
L_S	Internal Source Inductance	—	7.5	—	nH	
C_{iss}	Input Capacitance	—	650	—	pF	$V_{GS} = 0V$
C_{oss}	Output Capacitance	—	270	—		$V_{DS} = -25V$
C_{rss}	Reverse Transfer Capacitance	—	120	—		$f = 1.0\text{MHz}$, see Fig.5

Diode Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	-18	A	MOSFET symbol showing the integral reverse p-n junction diode.
	Pulsed Source Current (Body Diode) ①	—	—	-64		
V_{SD}	Diode Forward Voltage	—	—	-1.6	V	$T_J = 25^\circ\text{C}, I_S = -9.6\text{A}, V_{GS} = 0V$ ④
t_{rr}	Reverse Recovery Time	—	51	77	ns	$T_J = 25^\circ\text{C}, I_F = -9.6\text{A}$
Q_{rr}	Reverse Recovery Charge	—	110	160	nC	$di/dt = 100\text{A}/\mu\text{s}$ ④
t_{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

Notes:

① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11).
 ② Starting $T_J = 25^\circ\text{C}$, $L = 2.8\text{mH}$
 $R_G = 25\Omega$, $I_{AS} = -6.6\text{A}$ (See Figure 12)
 ③ $I_{SD} \leq -6.6\text{A}$, $di/dt \leq -240\text{A}/\mu\text{s}$, $V_{DD} \leq V_{(\text{BR})\text{DSS}}$,
 $T_J \leq 150^\circ\text{C}$

④ Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.
 ⑤ This is applied for I-PAK, L_S of D-PAK is measured between lead and center of die contact.
 ⑥ Uses IRF9Z24N data and test conditions.

** When mounted on 1" square PCB (FR-4 or G-10 Material).
 For recommended footprint and soldering techniques refer to application note #AN-994.

Qualification Information[†]

Qualification Level		Automotive (per AEC-Q101) ^{††}	
		Comments: This part number(s) passed Automotive qualification. IR's Industrial and Consumer qualification level is granted by extension of the higher Automotive level.	
Moisture Sensitivity Level	D PAK	MSL1	
	I-PAK	N/A	
ESD	Machine Model	Class M3 (250V) (per AEC-Q101-002)	
	Human Body Model	Class H1B (800V) (per AEC-Q101-001)	
	Charged Device Model	Class C5 (2000V) (per AEC-Q101-005)	
RoHS Compliant		Yes	

[†] Qualification standards can be found at International Rectifier's web site: <http://www.irf.com/>

^{††} Exceptions to AEC-Q101 requirements are noted in the qualification report.

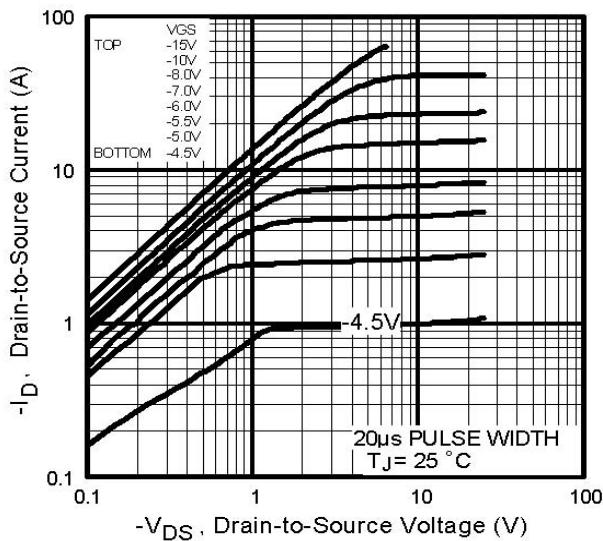


Fig 1. Typical Output Characteristics

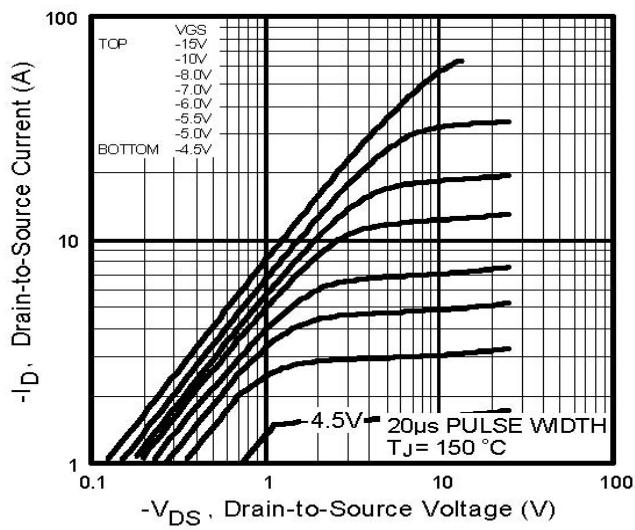


Fig 2. Typical Output Characteristics

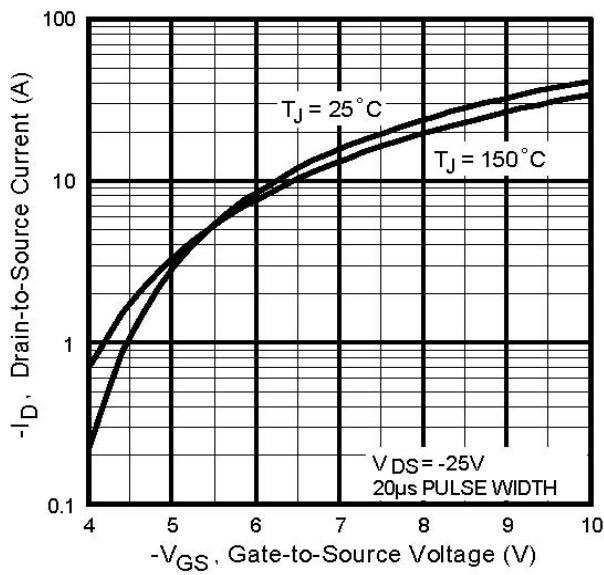


Fig 3. Typical Transfer Characteristics

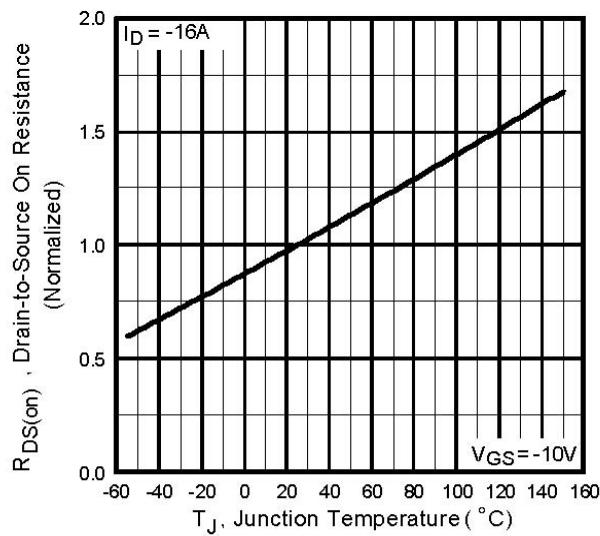


Fig 4. Normalized On-Resistance
Vs. Temperature

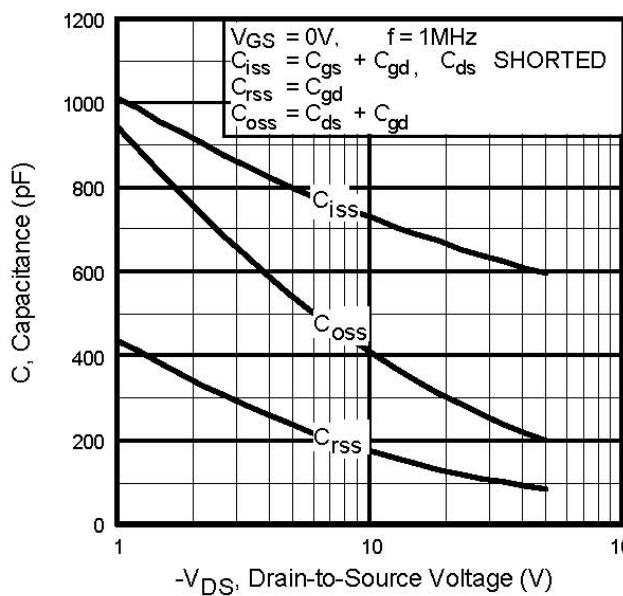


Fig 5. Typical Capacitance Vs.
Drain-to-Source Voltage

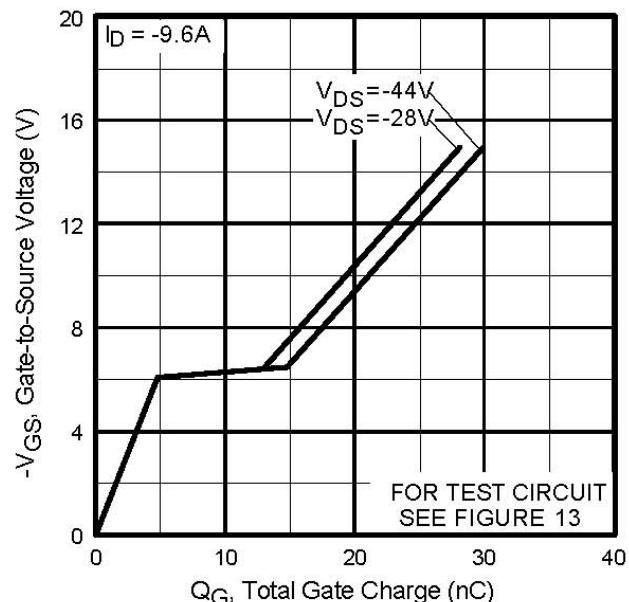


Fig 6. Typical Gate Charge Vs.
Gate-to-Source Voltage

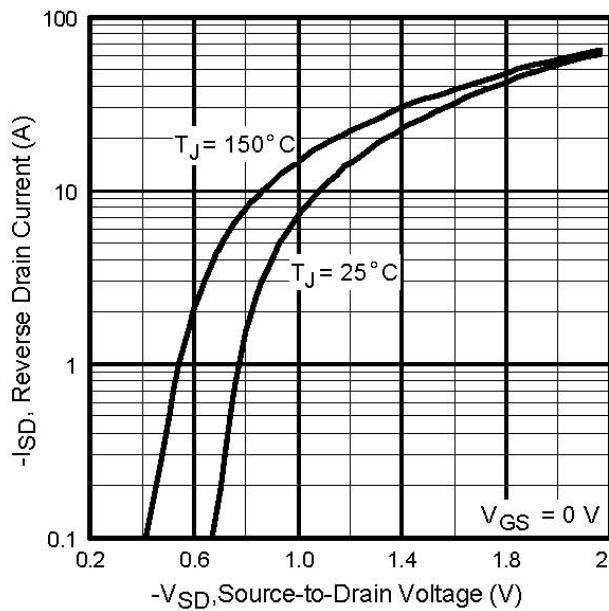


Fig 7. Typical Source-Drain Diode
Forward Voltage

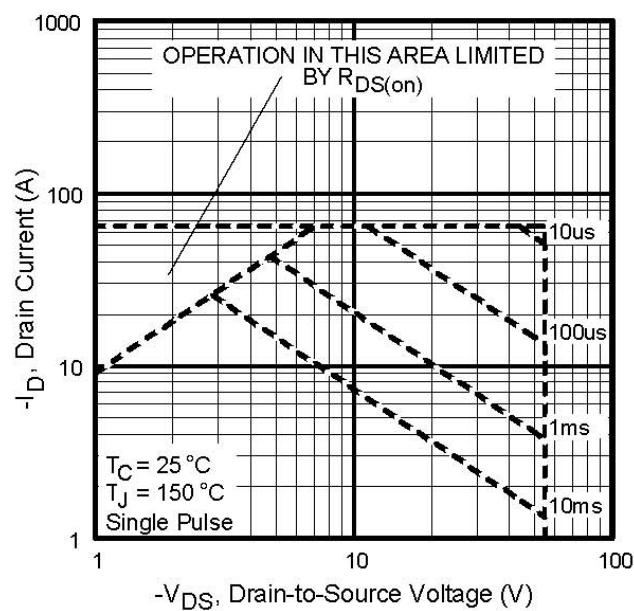


Fig 8. Maximum Safe Operating Area

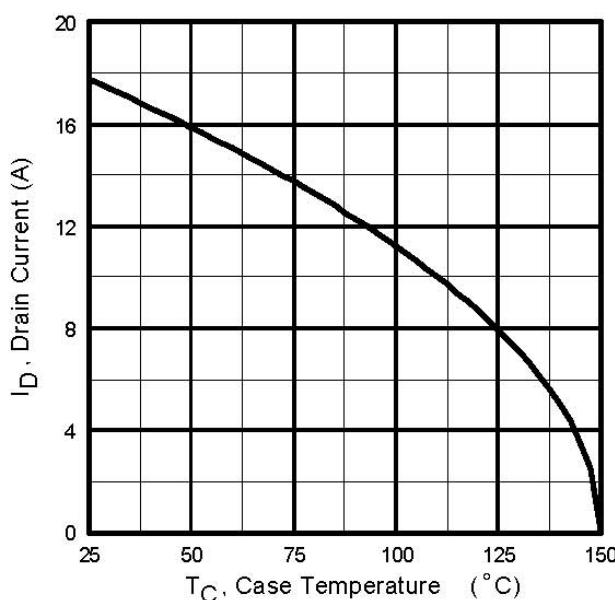


Fig 9. Maximum Drain Current Vs.
Case Temperature

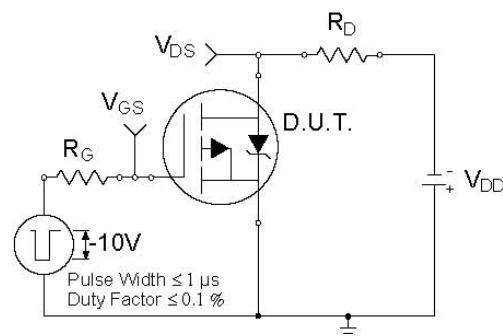


Fig 10a. Switching Time Test Circuit

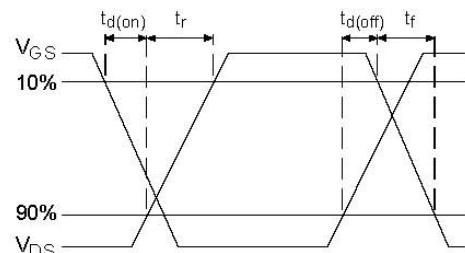


Fig 10b. Switching Time Waveforms

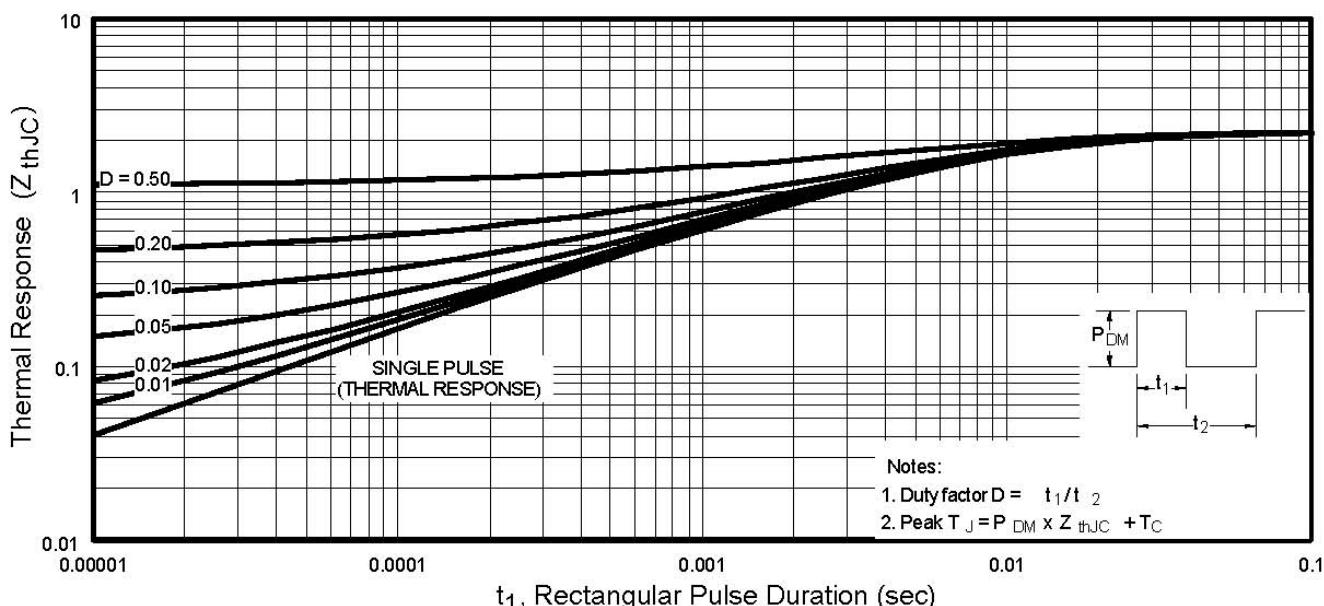


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

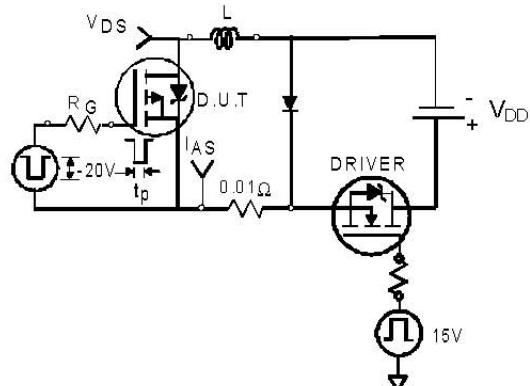


Fig 12a. Unclamped Inductive Test Circuit

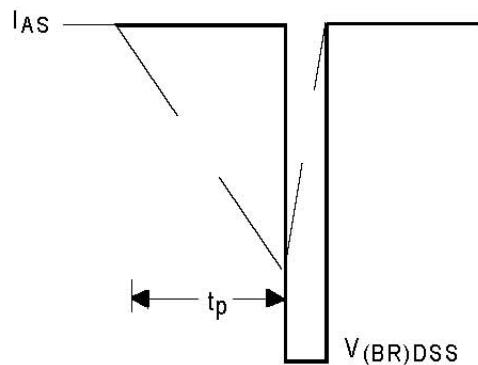


Fig 12b. Unclamped Inductive Waveforms

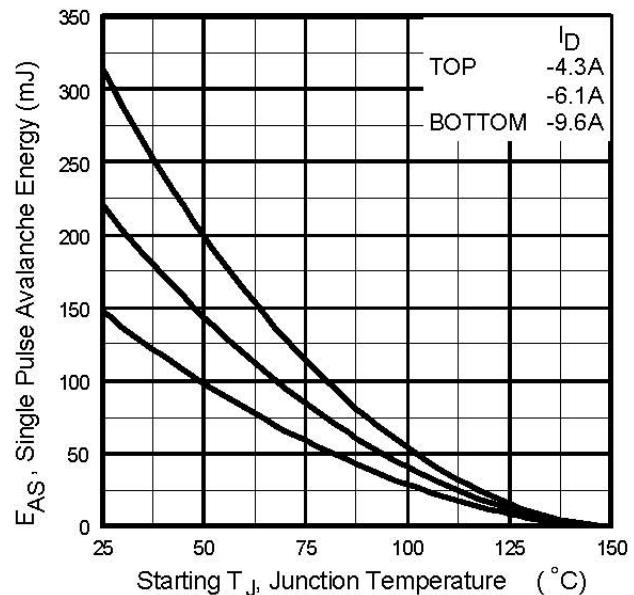


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

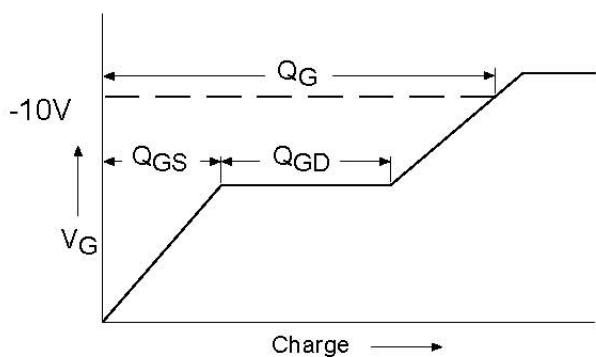


Fig 13a. Basic Gate Charge Waveform

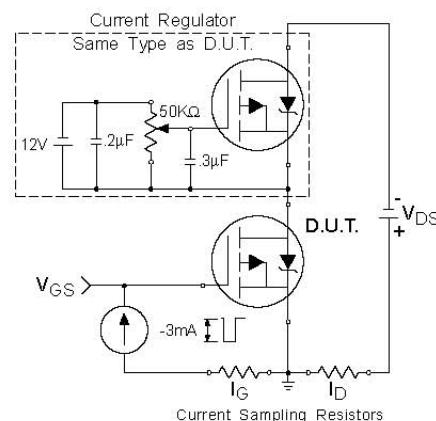
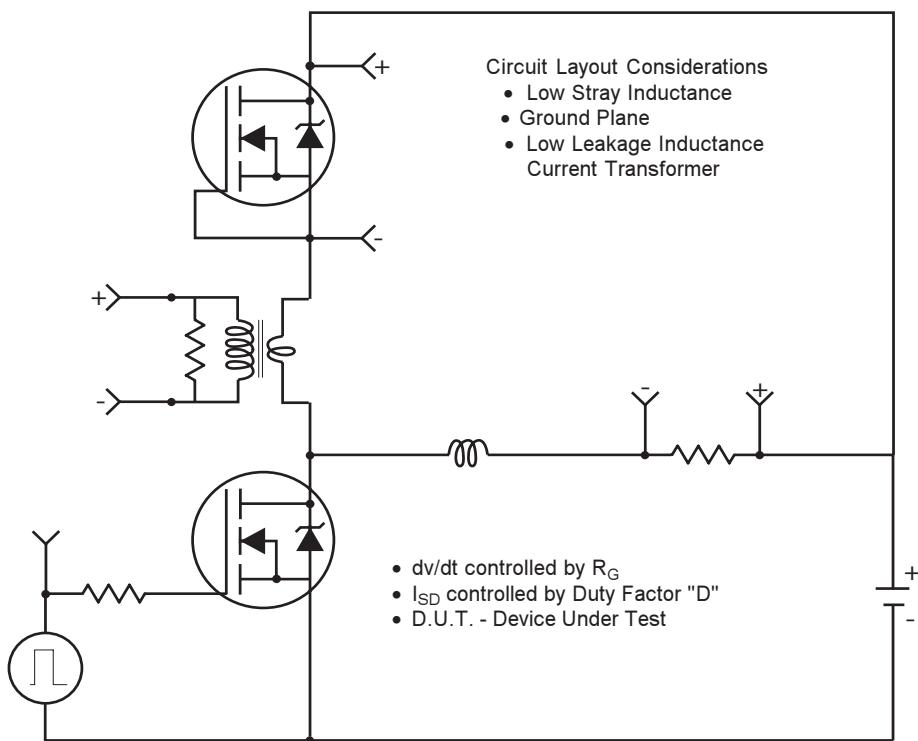


Fig 13b. Gate Charge Test Circuit

Peak Diode Recovery dv/dt Test Circuit

* Reverse Polarity for P-Channel

** Use P-Channel Driver for P-Channel Measurements

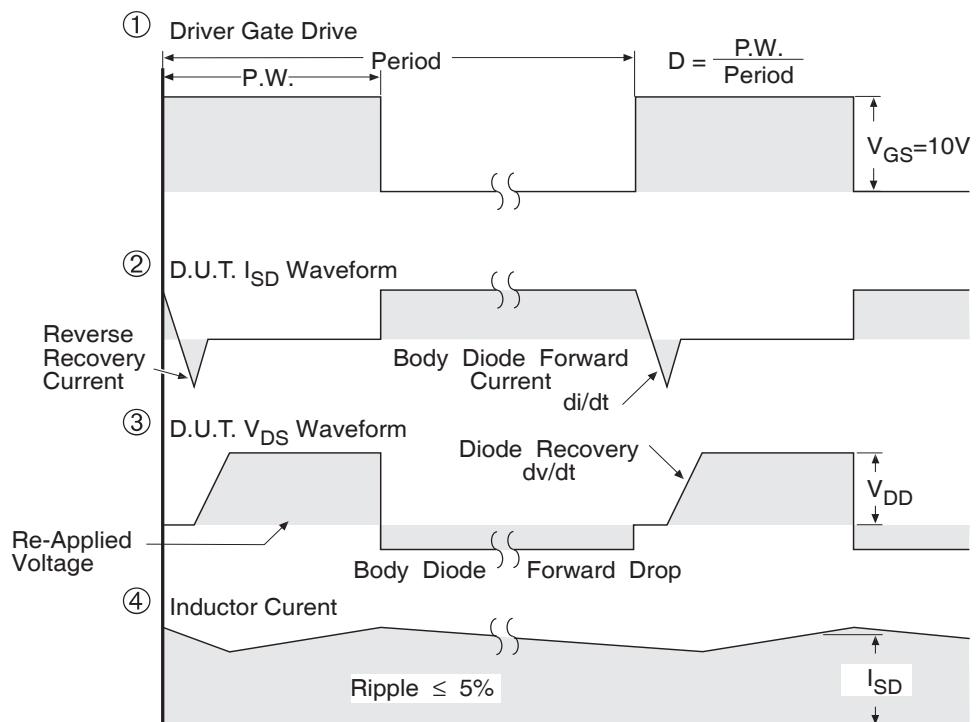
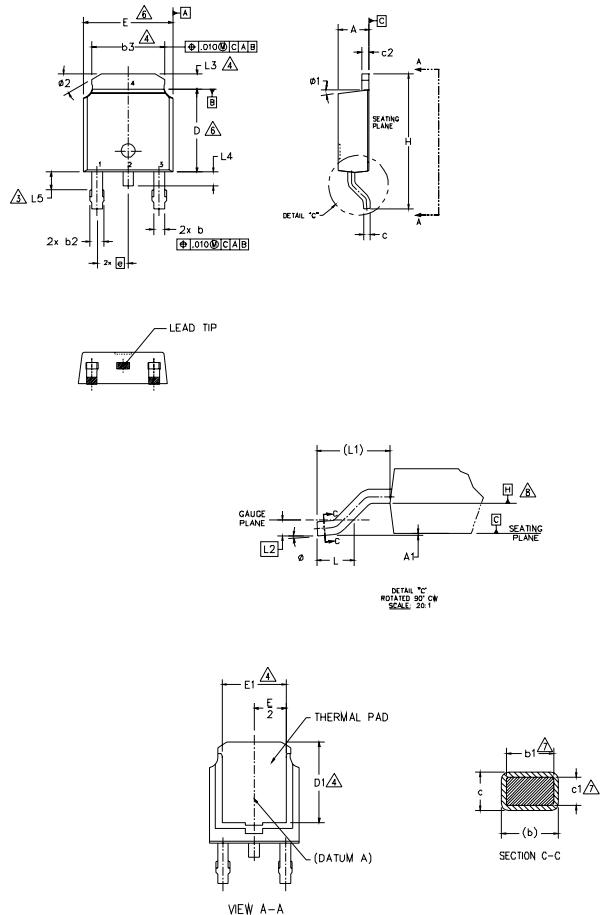
*** $V_{GS} = 5.0V$ for Logic Level and 3V Drive Devices

Fig 14 For P Channel HEXFETS

D-Pak (TO-252AA) Package Outline

Dimensions are shown in millimeters (inches)



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. DIMENSION ARE SHOWN IN INCHES [MILLIMETERS]
3. \triangle LEAD DIMENSION UNCONTROLLED IN L5.
4. \triangle DIMENSION D1, E1, L3 & b3 ESTABLISH A MINIMUM MOUNTING SURFACE FOR THERMAL PAD.
5. SECTION C-C DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .005 AND 0.10 [0.13 AND 0.25] FROM THE LEAD TIP.
6. \triangle DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005 [0.13] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY.
7. \triangle DIMENSION b1 & c1 APPLIED TO BASE METAL ONLY.
8. \triangle DATUM A & B TO BE DETERMINED AT DATUM PLANE H.
9. OUTLINE CONFORMS TO JEDEC OUTLINE TO-252AA.

S Y M B O L	DIMENSIONS				N O T E S	
	MILLIMETERS		INCHES			
	MIN.	MAX.	MIN.	MAX.		
A	2.18	2.39	.086	.094		
A1	—	0.13	—	.005		
b	0.64	0.89	.025	.035		
b1	0.65	0.79	.025	.031	7	
b2	0.76	1.14	.030	.045		
b3	4.95	5.46	.195	.215	4	
c	0.46	0.61	.018	.024		
c1	0.41	0.56	.016	.022	7	
c2	0.46	0.89	.018	.035		
D	5.97	6.22	.235	.245	6	
D1	5.21	—	.205	—	4	
E	6.35	6.73	.250	.265	6	
E1	4.32	—	.170	—	4	
e	2.29	BSC	.090	BSC		
H	9.40	10.41	.370	.410		
L	1.40	1.78	.055	.070		
L1	2.74	BSC	.108	REF.		
L2	0.51	BSC	.020	BSC		
L3	0.89	1.27	.035	.050	4	
L4	—	1.02	—	.040		
L5	1.14	1.52	.045	.060	3	
\emptyset	0°	10°	0°	10°		
\emptyset 1	0°	15°	0°	15°		
\emptyset 2	25°	35°	25°	35°		

LEAD ASSIGNMENTS

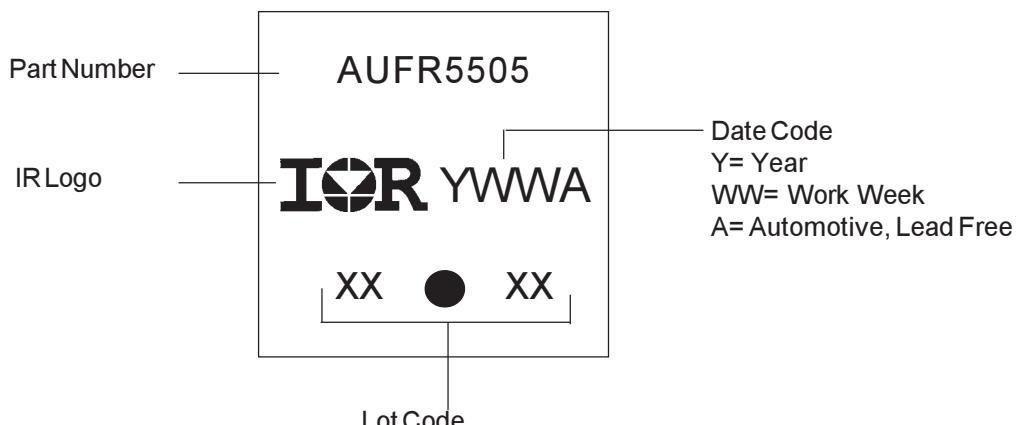
HEXFET

1. GATE
2. DRAIN
3. SOURCE
4. DRAIN

IGBT & CoPAK

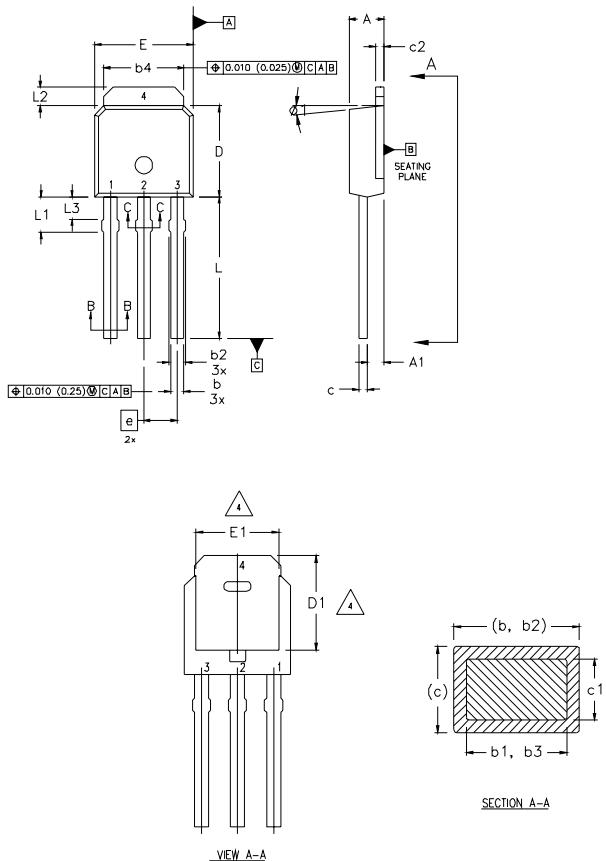
1. GATE
2. COLLECTOR
3. Emitter
4. COLLECTOR

D-Pak (TO-252AA) Part Marking Information



Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>
www.irf.com

I-Pak (TO-251AA) Package Outline (Dimensions are shown in millimeters (inches)



NOTES:

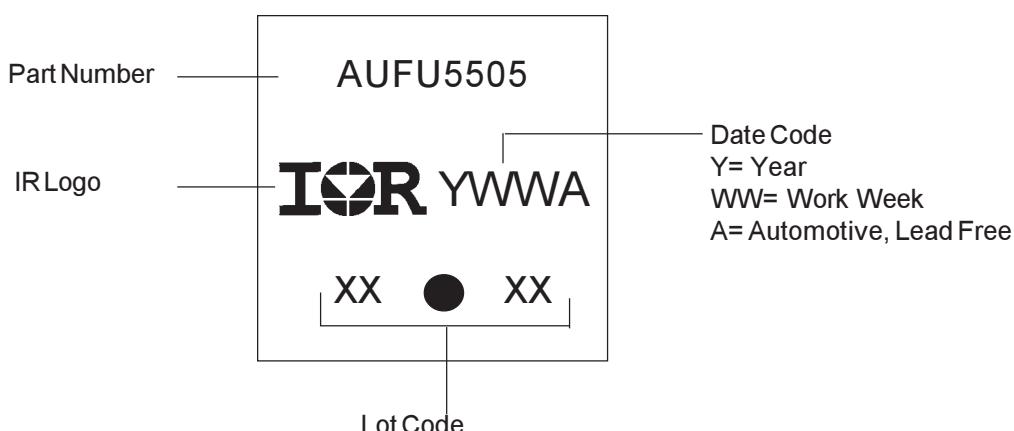
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5 M- 1994.
2. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
3. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.005" (0.127) PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
4. THERMAL PAD CONTOUR OPTION WITHIN DIMENSION b4, L2, E1 & D1.
5. LEAD DIMENSION UNCONTROLLED IN L3.
6. DIMENSION b1, b3 APPLY TO BASE METAL ONLY.
7. OUTLINE CONFORMS TO JEDEC OUTLINE TO-251AA.
8. CONTROLLING DIMENSION : INCHES.

LEAD ASSIGNMENTS

SYMBOL	DIMENSIONS				NOTES	
	MILLIMETERS		INCHES			
	MIN.	MAX.	MIN.	MAX.		
A	2.18	2.39	0.086	.094		
A1	0.89	1.14	0.035	0.045		
b	0.64	0.89	0.025	0.035		
b1	0.64	0.79	0.025	0.031	4	
b2	0.76	1.14	0.030	0.045		
b3	0.76	1.04	0.030	0.041		
b4	5.00	5.46	0.195	0.215	4	
c	0.46	0.61	0.018	0.024		
c1	0.41	0.56	0.016	0.022		
c2	.046	.066	0.018	0.035		
D	5.97	6.22	0.235	0.245	3, 4	
D1	5.21	—	0.205	—	4	
E	6.35	6.73	0.250	0.265	3, 4	
E1	4.32	—	0.170	—	4	
e	2.29		0.090	BSC		
L	8.89	9.60	0.350	0.380		
L1	1.91	2.29	0.075	0.090		
L2	0.89	1.27	0.035	0.050	4	
L3	1.14	1.52	0.045	0.060	5	
Ø1	0"	15"	0"	15"		

HEXFET
 1.- GATE
 2.- DRAIN
 3.- SOURCE
 4.- DRAIN

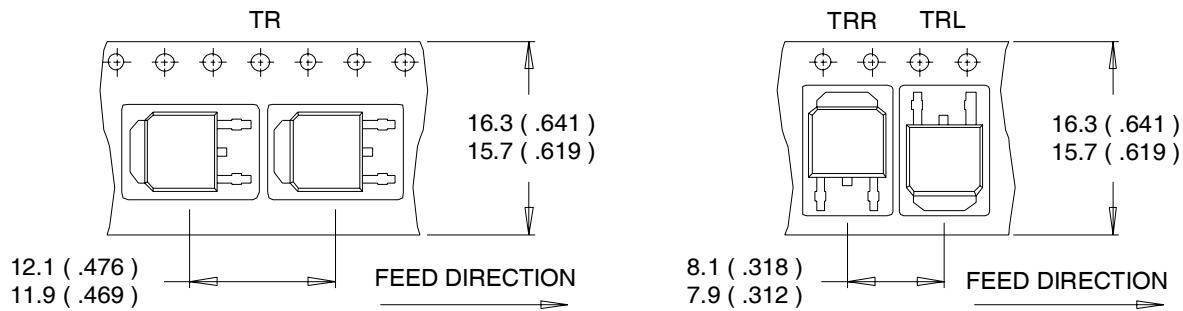
I-Pak (TO-251AA) Part Marking Information



Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>

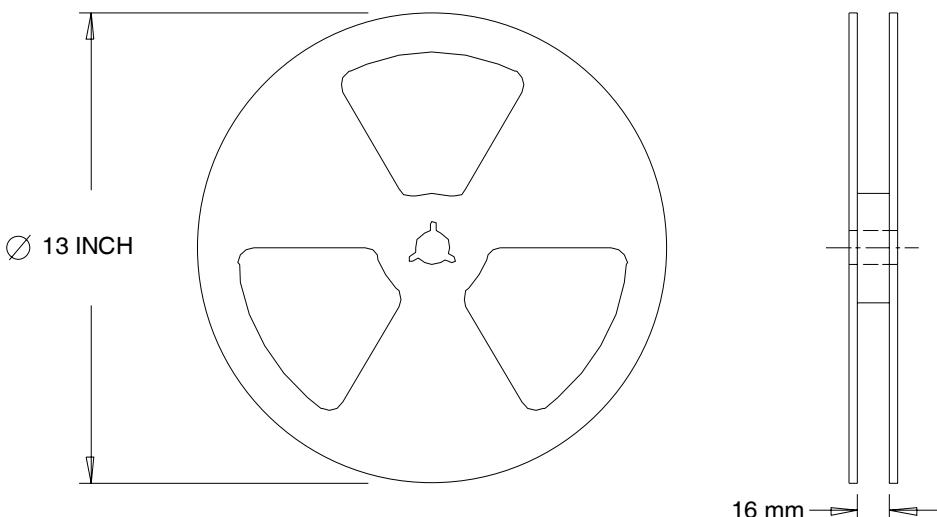
D-Pak (TO-252AA) Tape & Reel Information

Dimensions are shown in millimeters (inches)



NOTES :

1. CONTROLLING DIMENSION : MILLIMETER.
2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



NOTES :

1. OUTLINE CONFORMS TO EIA-481.

Ordering Information

Base part	Package Type	Standard Pack		Complete Part Number
		Form	Quantity	
AUIRFR5505	DPak	Tube	75	AUIRFR5505
		Tape and Reel	2000	AUIRFR5505TR
		Tape and Reel Left	3000	AUIRFR5505TRL
		Tape and Reel Right	3000	AUIRFR5505TRR
AUIRFU5505	IPak	Tube	75	AUIRFU5505

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For technical support, please contact IR's Technical Assistance Center
<http://www.irf.com/technical-info/>

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Tel: (310) 252-7105